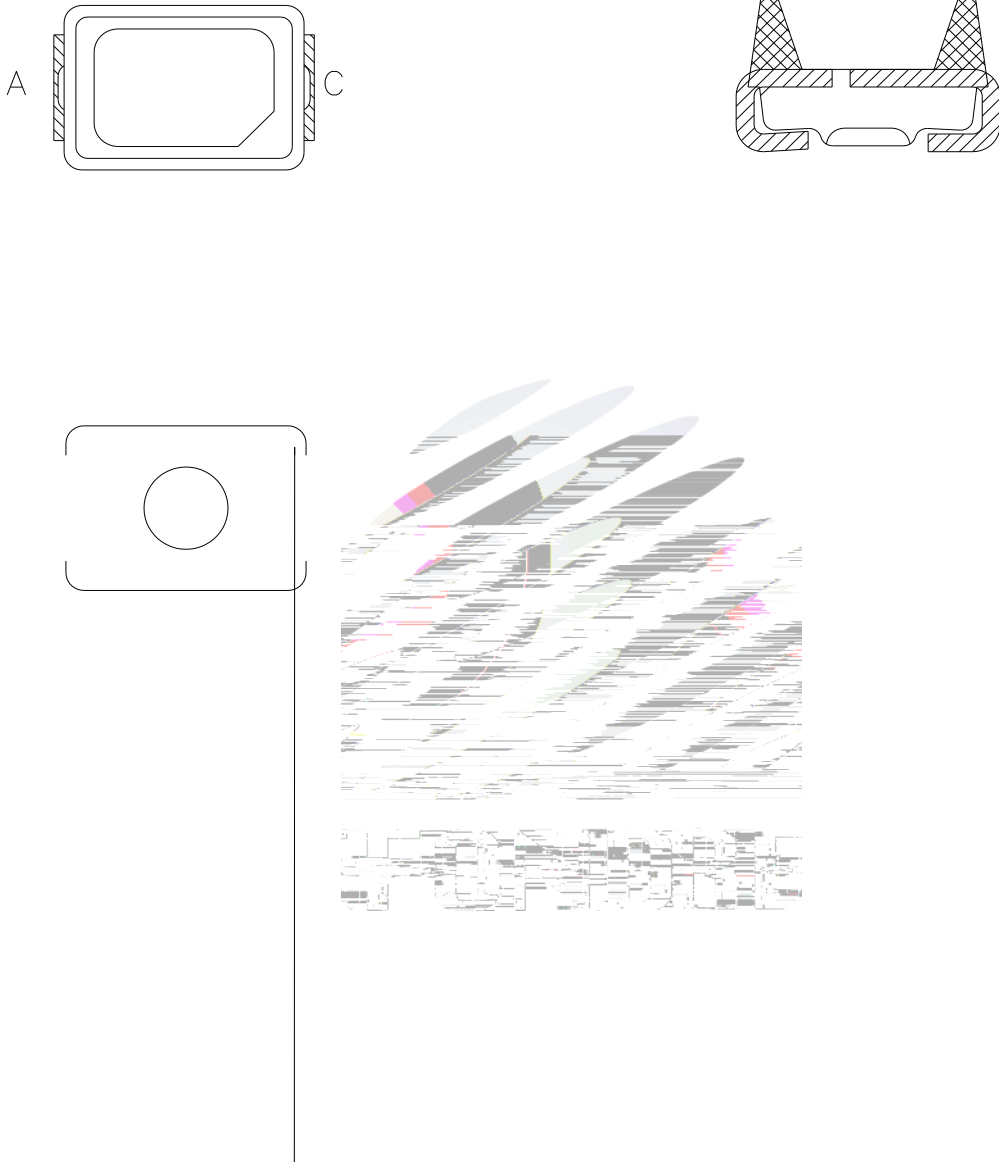






1.4 Package Dimension 封装尺寸



Notes 备注:

1. All dimensions units are millimeters. 所有尺寸标注单位为毫米
2. All dimensions tolerances are 0.20mm unless otherwise noted. 除特别标注外, 所有尺寸公差为±0.20 毫米



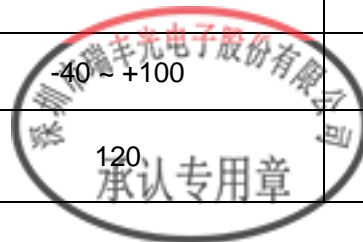
1.5 Product Parameters 产品参数

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

Item 项目	Symbol 符号	Test Condition 测试条件	Value			Unit 单位
			Min. (最小值)	Typ. (典型值)	Max. (最大值)	
Forward Voltage (正向电压)	V _F	I _F =20mA	2.6	3.0	3.2	V
Reverse Current (反向电流)	I _R	V _R =5V	---	---	10	uA
Luminous Intensity (发光强度)	I _V	I _F =20mA	350	400	650	mcd
Dominant wavelength (主波长)	WD	I _F =20mA	465	468	472.5	nm
Viewing Angle (发光角度)	θ	I _F =20mA	---	120	---	deg
Thermal Resistance. (热阻)	R _{THJ-S}	I _F =20mA	---	---	300	°C/W

Table 1-2 Absolute Maximum Ratings at Ts=25°C 绝对最大值

Parameter (参数)	Symbol (符号)	Rating (值)	Unit (单位)
Power Dissipation (功耗)	P _D	102	mW
Forward Current (正向电流)	I _F	30	mA
Peak Forward Current (峰值电流)	I _{FP}	100	mA
Reverse Voltage (反向电压)	V _R	5	V
Electrostatic Discharge (HBM) (耐受电压)	V _{ESD}	8000	V
Operating Temperature (操作温度)	T _{OPR}	-40 ~ +100	°C
Storage Temperature (储存温度)	T _{STG}	-40 ~ +100	°C
Junction Temperature (结温)	T _J	120	°C



Notes 备注:

1. 1/10 Duty cycle, 10ms pulse width. 脉宽10ms,占空比1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. 以上所示电压测量误差 $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . 以上所示坐标测量误差 ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. 上述发光强度的测试允许公差为 $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值。
6. All measurements were made under the standardized environment of Refond. 标准测试平台。
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED 使用的最大电流需要根据散热条件确定, 结温不能超过最大值。
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handing is needed. 90%的LED 通过人体模式ESD8000V测试, 在操作时请注意静电防护。

1.6Bin Range Of Forward Voltage and Luminous Intensity and Dominant wavelength (IF=20mA)电压与发光强度与主波长分 BIN 范围(IF=20mA)

Table 1-3

V _F V	G1	G2	H1	H2
	2.8-2.9	2.9-3.0	3.0-3.1	3.1-3.2
IV mcd	J1	J2	K1	
	350-430	430-530	530-650	
WD(nm)	D1	D2	E1	
	465-467.5	467.5-470	470-472.5	



1.7 Typical Optical



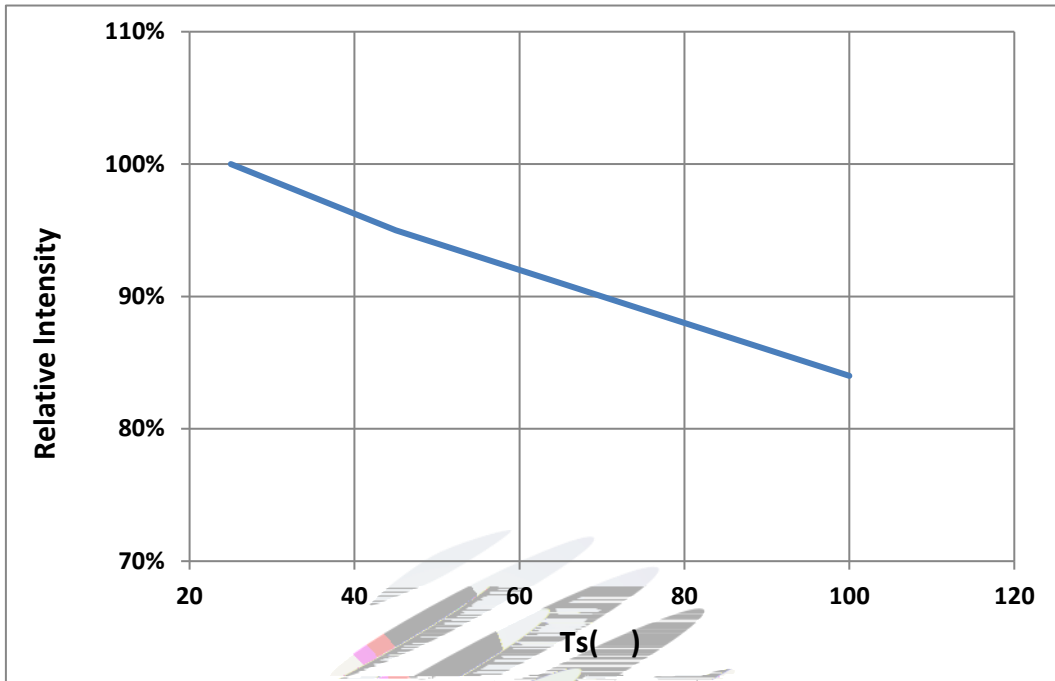


Fig. 1-8 Solder Temperature Vs Relative Intensity 管脚温度与相对光强特性曲线

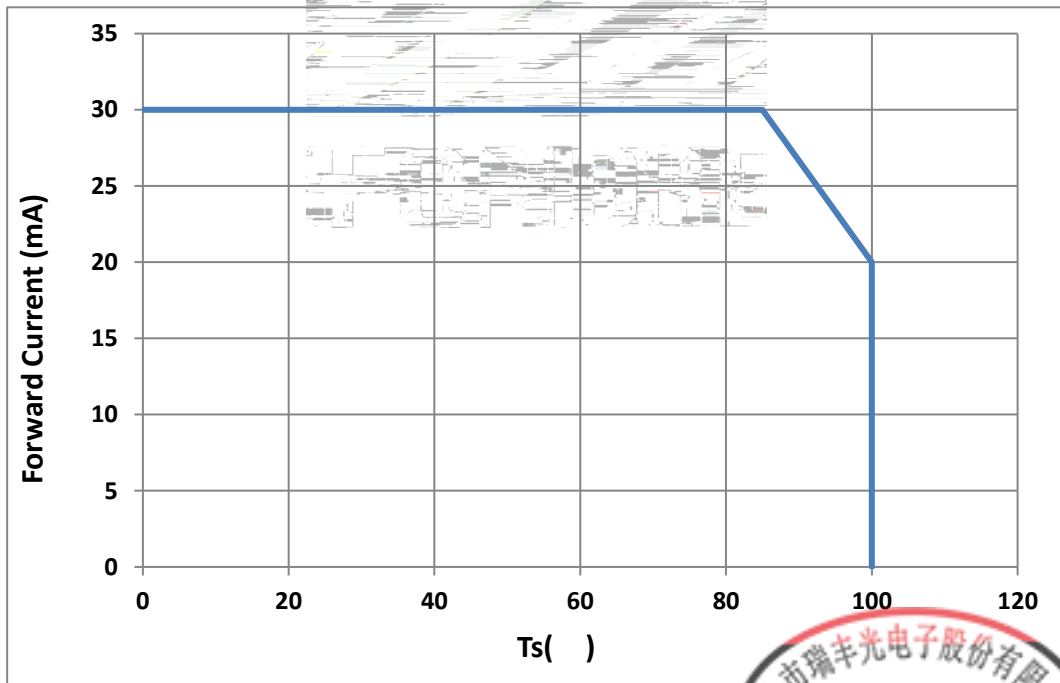
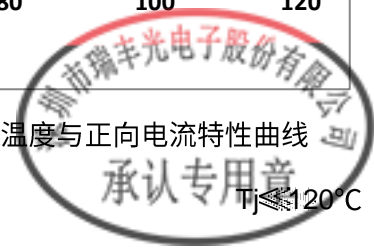


Fig. 1-9 Solder Temperature Vs Forward Current 管脚温度与正向电流特性曲线



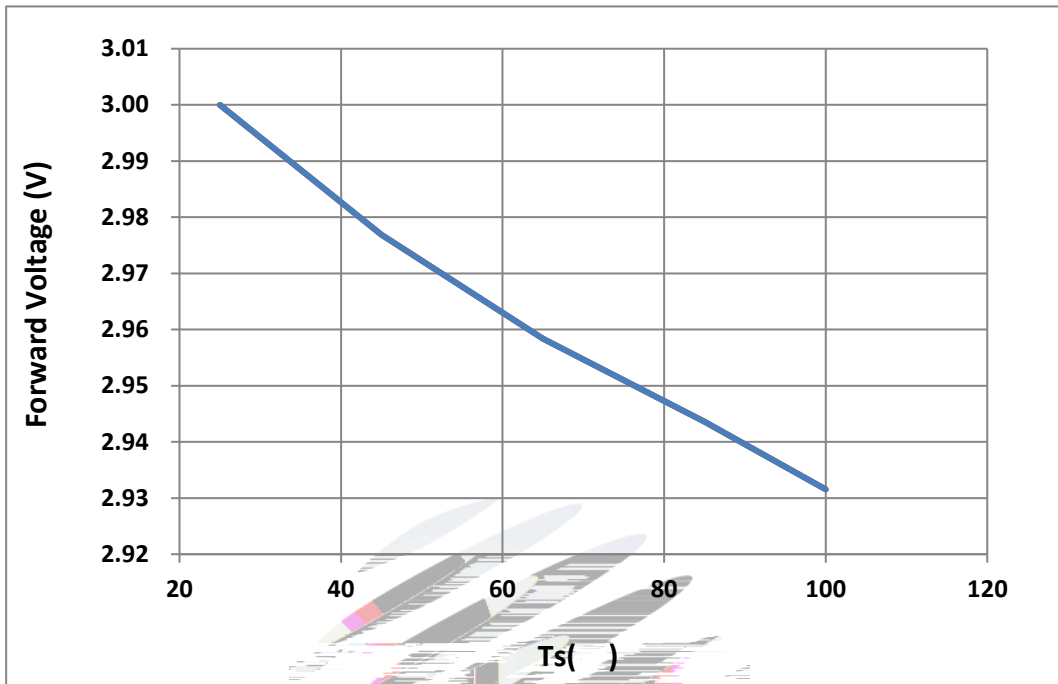


Fig. 1-10 Forward Voltage Vs Solder Temperature 电压与管脚温度特性曲线

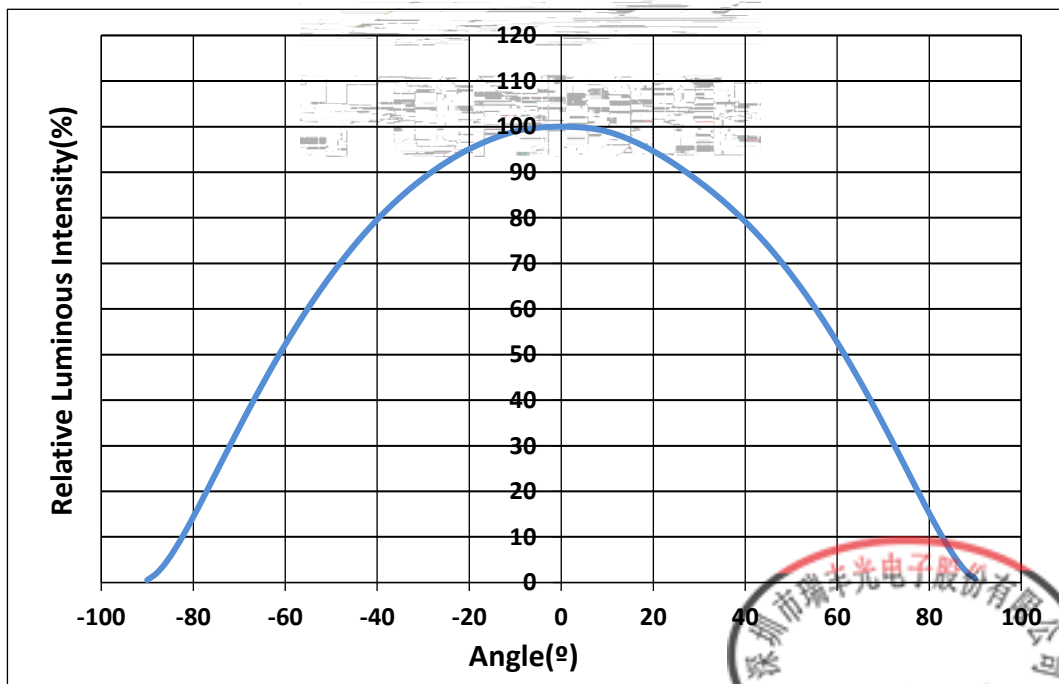
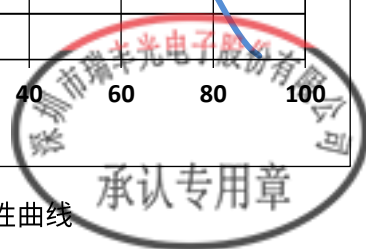


Fig. 1-11 Radiation diagram 辐射特性曲线



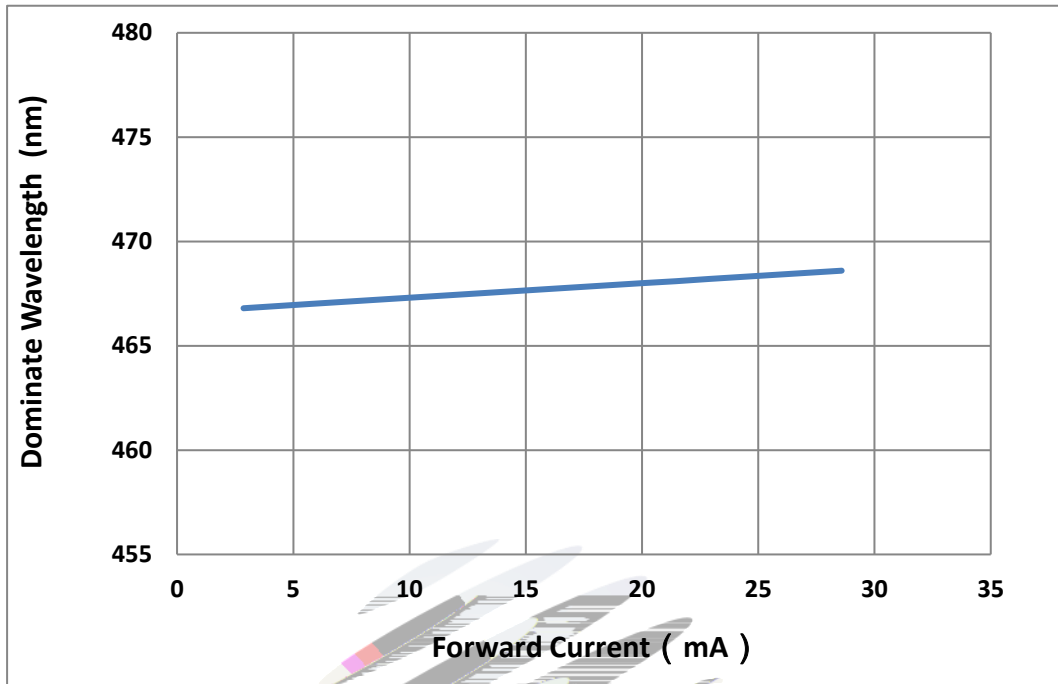


Fig. 1-12 Forward current VS Dominate wavelength 正向电流与主波长特性曲线 (Ts=25°C)



Fig. 1-13 Spectrum Distribution 光谱分布特性曲线

2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package: 3000pcs/reel. 包装每卷 。

2.1.1 Carrier Tape Dimension 载带尺寸

)

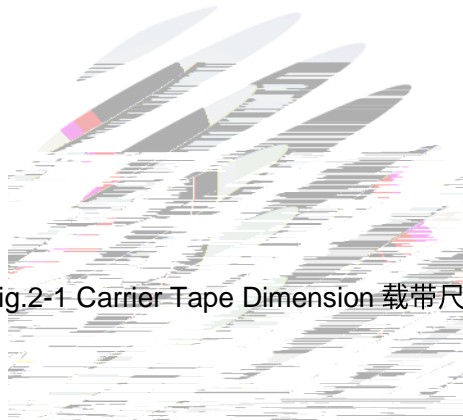


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2 Reel Dimension 卷盘尺寸

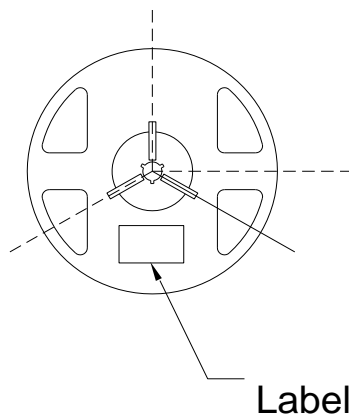


Fig.2-2 Reel Dimension 卷盘尺寸



Table 2-1 Reel Dimension 卷盘尺寸

A	8.0±0.1mm
B	178.0±1.0mm
C	60.0±1.0mm
D	13.0±0.5mm

Notes 备注:

The tolerances unless mentioned ±0.1mm. Unit : mm 注: 未注公差为±0.1毫米, 尺寸单位: 毫米。



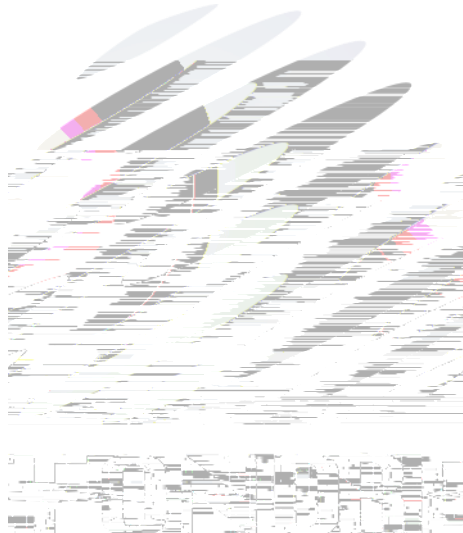
2.1.3 Label Form Specification



2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Reliability Test Items And Conditions 信赖性测试项目及条件

Test Items 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260°Cmax T=10 sec	2times	20pcs.	0/1



2.5 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria For Judging Damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	V_F	$I_F=20mA$	-	U.S.L*)x1.1
Reverse Current 反向电流	I_R	$V_R = 5V$	-	U.S.L*)x2.0
Luminous Intensity 发光强度	I_V	$I_F=20mA$	L.S.L*)x0.7	-

Notes 备注:

- 1.U.S.L: Upper standard level 规格上限 L.S.L: Lower standard level 规格下限
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental Platform, the reliability experiment was taken under good heat dissipation conditions. When customers applies The LED to the series and parallel circuit, should take consideration of all the factors such as the current, Voltage distribution, heat dissipation and others.以上可靠性测试是基于瑞丰现有实验平台单颗/条 LED 在良好散热条件验证下的结果。客户端将 LED 应用于串、并联线路时，需自行评估电流、电压分配、散热等问题
- 3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。



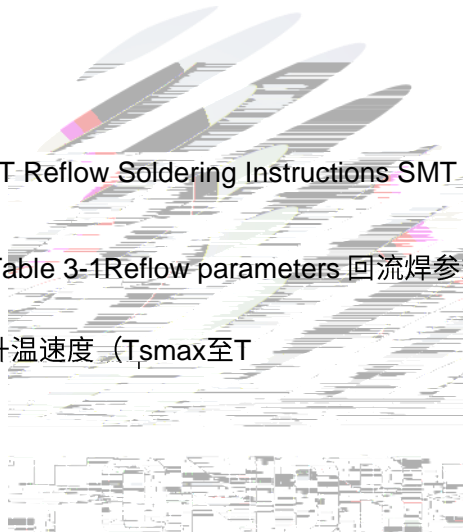
3.SMTReflow Soldering Instructions SMT 回流焊说明

3.1SMT Reflow Soldering Instructions SMT 回流焊说明

Fig.3-1SMT Reflow Soldering Instructions SMT 回流焊说明

Table 3-1Reflow parameters 回流焊参数

Average temperature rise speed平均升温速度 (T_{smax}至T



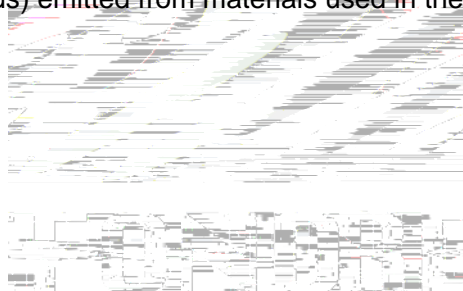
4. Handling Precautions 产品使用注意事项

4.1 Handling Precautions 产品使用注意事项

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM. 这只是一个建议, 不作任何品质担保。

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. 为了防止外界物质进入 LED 内部以造成 LED 的损坏, 外部环境中所用零件等等, 总的溴元素含量要求小于 900PPM, 单一氯元素含量要求小于 900PPM, 溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议, 不作任何品质担保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can 0 596.04 842.04



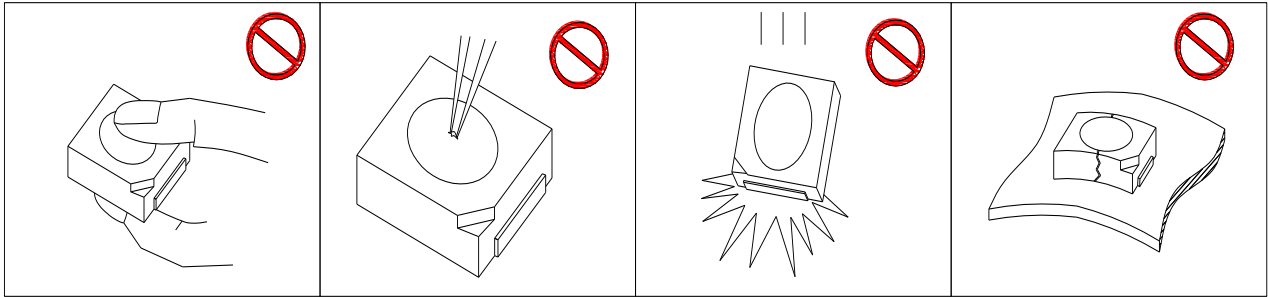


Fig 4-1 Handling Precautions 产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. 设计电路时，通过 LED 的电流不能超过规定的最大值，同时，还需使用保护电阻，否则，微小的电压变化将会引起较大电流变化，可能导致产品损毁。电路设计必须保证只有在开启或者关闭的时候出现正向电压的变化，不要施加反压，否则会损坏 LED。

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED 亮度会因为自身的发热和环境的温度改变而改变，温度升高会降低 LED 发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

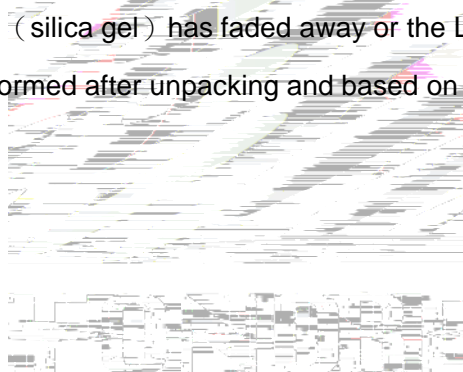
(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意。当对产品洁净度要求较高时，回流焊以后需要采用恰当的清洗方式，我们推荐用异丙醇作清洗剂，如需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对 LED 带来损害，不推荐这种清洗方式。



Table 4-1 Storage 儲存

Conditions 种类		Temperature	Humidity 湿度	Time 时间
Storage 儲存	Before Opening Aluminum Bag 拆包前	≤30°C	≤75%	Within 1 Year From Date
	After Opening Aluminum Bag 拆包后	≤30°C	≤60%	Recommended for use within 24 hours 建议24小时内使用
Baking 烘烤		60±5°C	-	≥24hours 大于24小时

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on MCID 32-BDC q266.45 552.19 75.264 60.02.





Declare 申明

This specification is written both in English and in Chinese and the latter is formal.
产品规格书以中英文方式书写，以后者为准。